



Advanced Materials for Power Electronics

Guest Editor:

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submissions:

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Message from the Guest Editor

The aim of this Special Issue on “Advanced Materials for Power Electronics” is to capture recent developments in all types of materials for advancing power electronics. These developments include wide bandgap semiconductors for devices, dielectrics for capacitors, soft magnetic materials for inductors and transformers, interconnect and encapsulation materials for packaging, thermal interface materials for cooling, and feedstock materials of additive manufacturing for power electronics packaging and integration. Manuscripts in the form of full research papers, communications, and review articles are encouraged.

Keywords

- wide band-gap semiconductor materials for power devices
- dielectrics for power electronics capacitors
- soft magnetic materials for power inductors and transformers
- die-attach, interconnect, and encapsulation materials for power packaging
- thermal interface materials for cooling
- feedstock materials of additive manufacturing for heterogeneous integration





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Message from the Editor-in-Chief

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